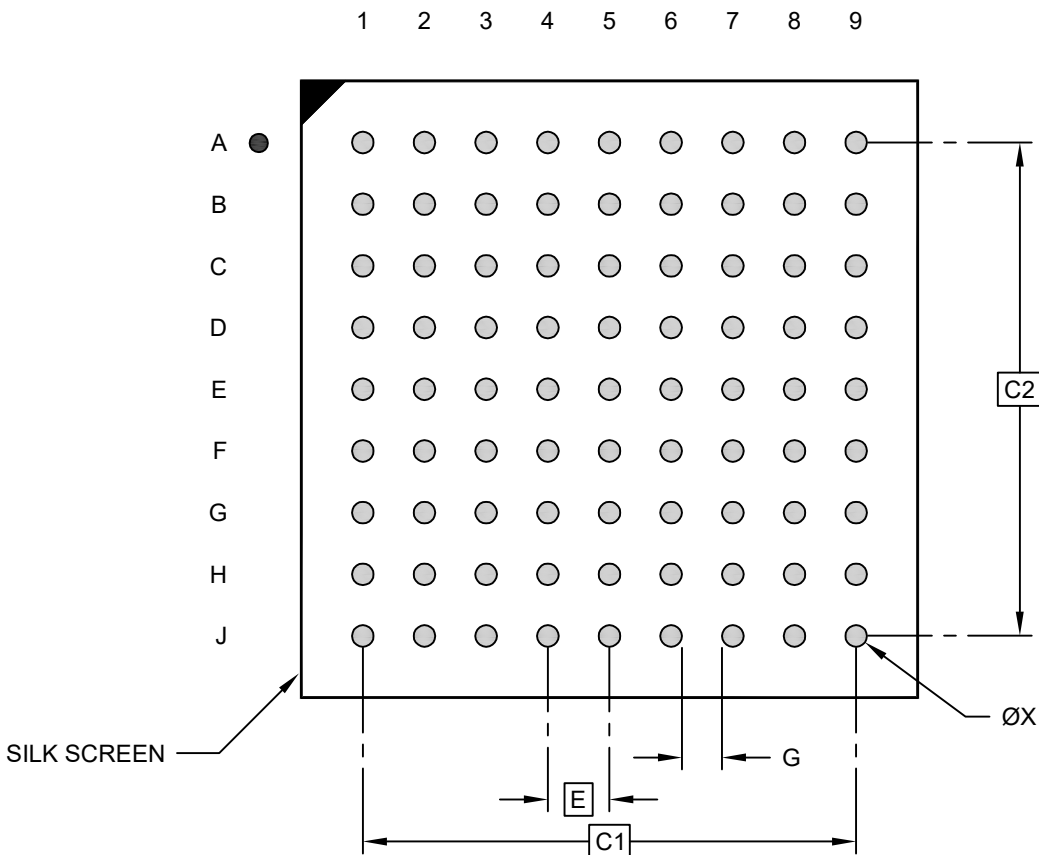


# 81-Ball Thin Fine-Pitch Ball Grid Array Package (4LB) - 10x10x1.2 mm Body [TFBGA]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.00 BSC		
Contact Pad Spacing	C1	8.00 BSC		
Contact Pad Spacing	C2	8.00 BSC		
Contact Pad Width (X81)	X			0.35
Contact Pad to Contact Pad	G	0.65		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.